WinWay

Your Trusted Partner in Semiconductor Testing

TWSE 6515

Investor Presentation

2026.03.09

Safe Harbor Notice

This presentation may contain forward-looking statements. All statements, other than statements of historical facts, that address activities, events or developments that WinWay Technology Co., Ltd. expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates and business plans) are forward-looking statements.

WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.

Company Information

Founded	Chairman & CEO	Business Operation
2001.4.10	Mark Wang	Design, manufacture, sale and service of test interface products
Employees	**Capital Stock**	**Registered Address**
1068	NTD 360,416,420	No.68, Chuangyi S. Rd, Nanzi Dist. Kaohsiung City, Taiwan

USA Branch Office

Kaohsiung Headquarter

Hsinchu Branch Office

Company Vision

Innovation

We deliver the best possible test tooling solutions to our customers through technological innovation.

Quality

We exceed customers' quality requirements by offering cost-effective total solutions and on-time delivery worldwide.

Service

We strive to become the world's leading professional testing service provider in all phases of IC testing.

Agenda

01

Global Presence

02

Industry Trend

03

Financial Performance

04

R&D Innovation

01 Global Presence

Global Service & Support Network

KH Spring Probe	KH Plant	Hsinchu Plant	Suzhou Plant	Renwu Plant
Spring Probe for Socket	Coaxial Socket HyperSocket™	Vertical Probe Card MEMS Probe Card	Coaxial Socket	Coaxial Socket

Semiconductor Test Interface Leadership

2024

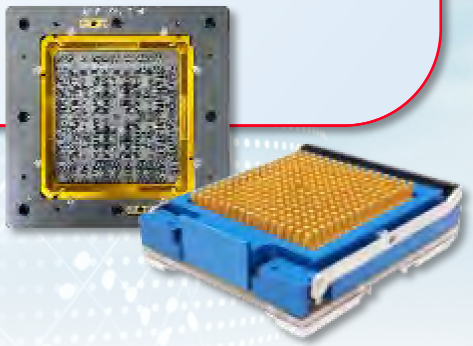
Test Socket Ranking

NO. 1

2024

Test and Burn-in Socket Ranking

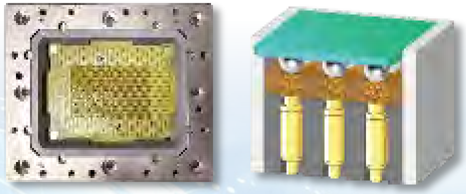
NO. 2



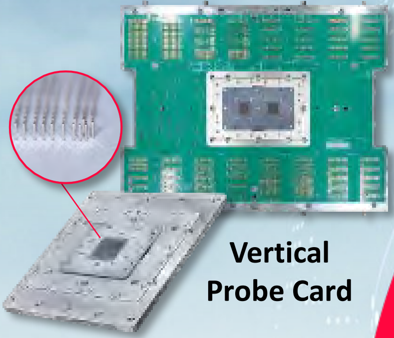
Source：Yole Intelligence, 2025/04

Your Trusted Partner in Semiconductor Testing

Plastic Socket & RF Socket



Coaxial Socket & HyperSocket™



Vertical Probe Card

Burn-in Socket

Wafer Sort

Final Test

SLT & SFT

Functional Burn-in

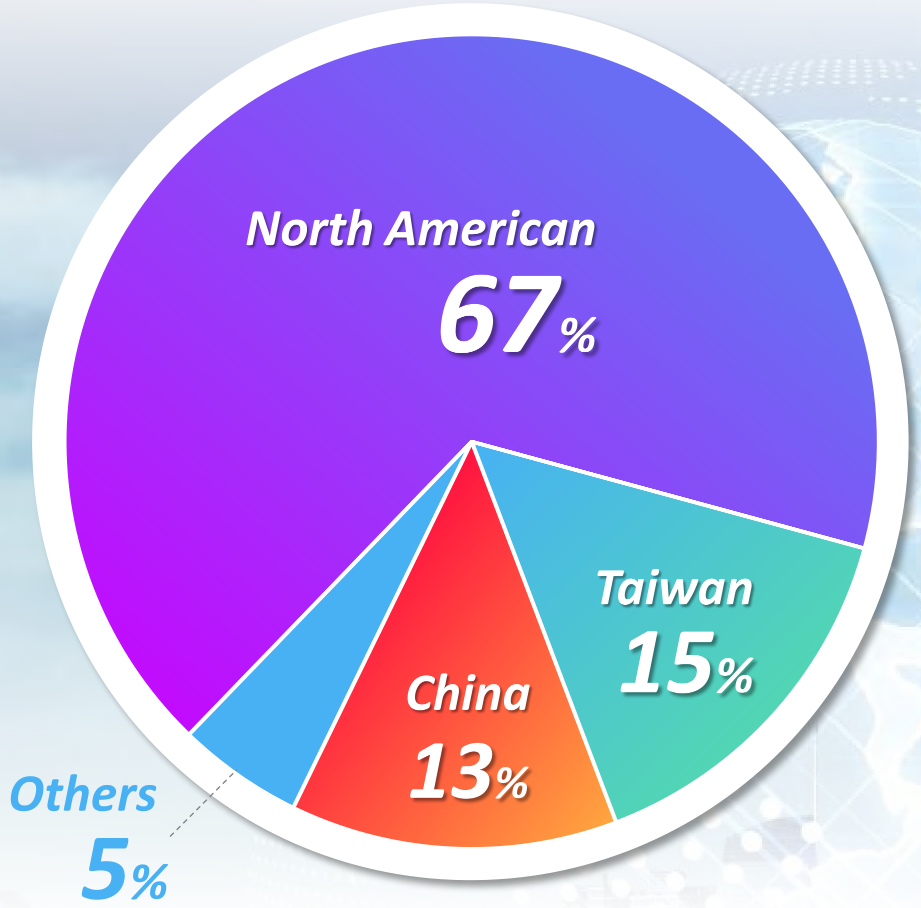
DFT Design For Testing

DFM Design For Manufacturing

WinWay
穎崴科技

Worldwide Customer

Year 2025



87% Top10 Customers

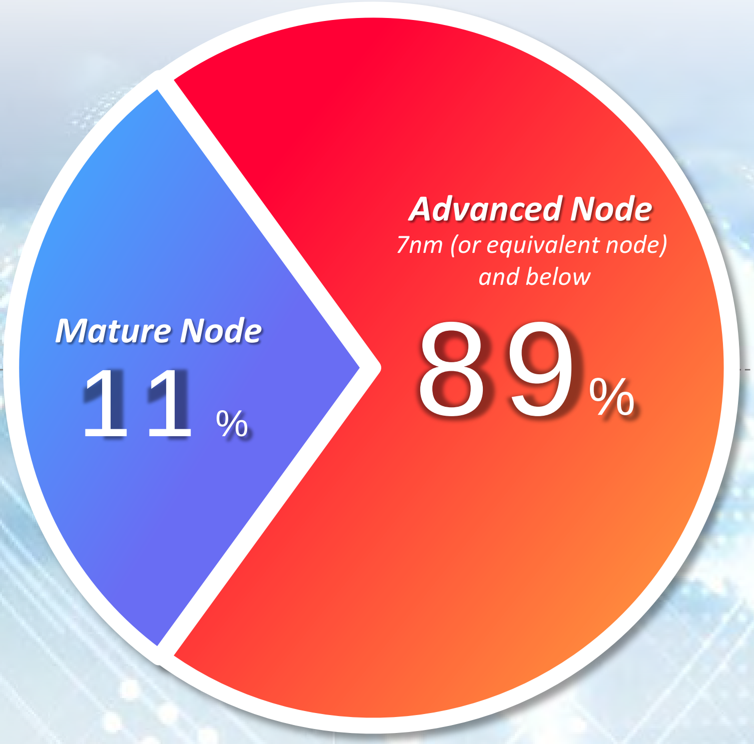
- AI
- ASIC
- CPU
- HPC
- AP
- GPU

200+ Active Customers

- IC Design
- Foundry
- OSAT
- CSP
- ASIC
- IDM

Bolstered by Advanced Technology

Year 2025



Automotive

Networking

IoT

DTV & STB

NAND Flash

AI

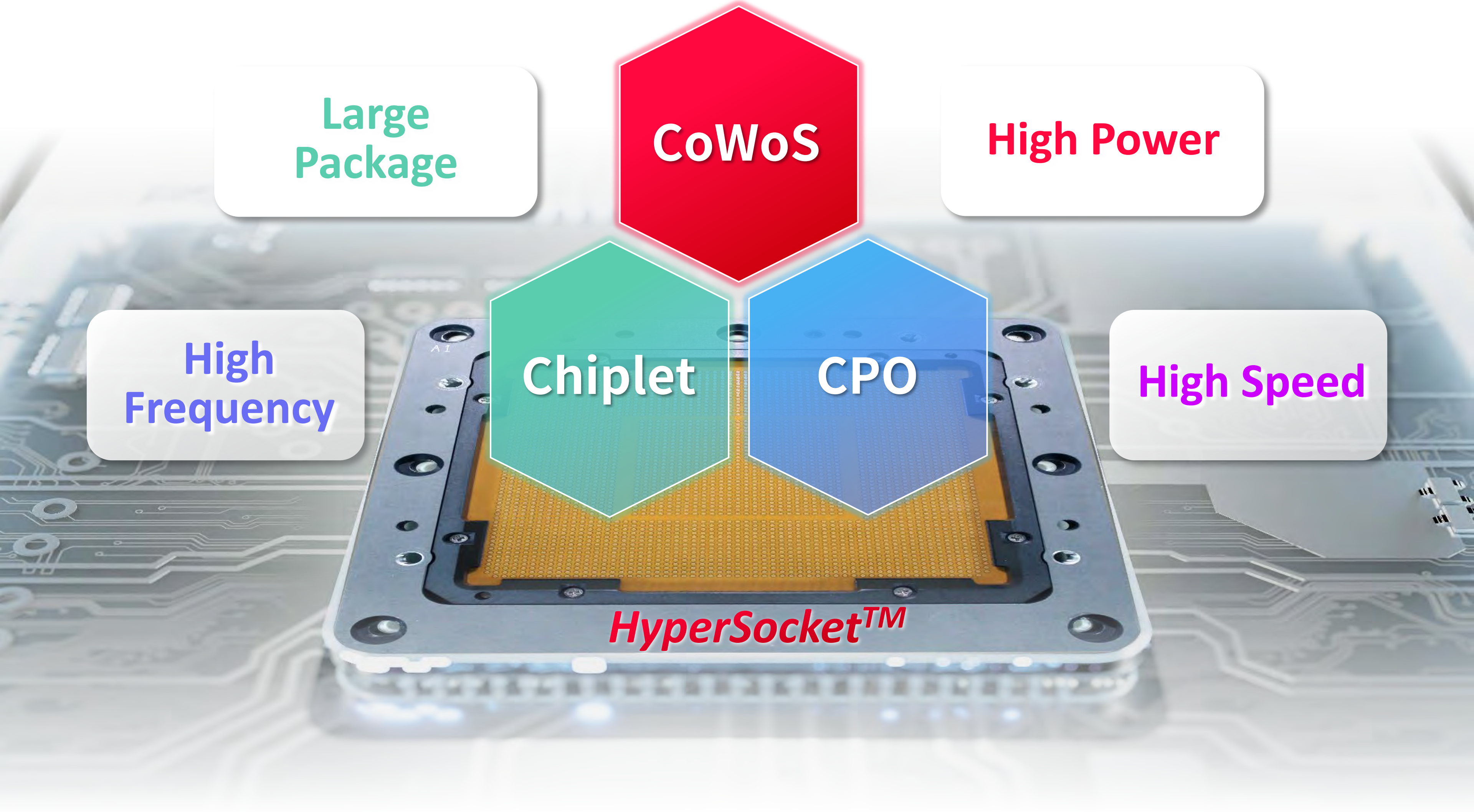
HPC

GPU

CPU

Smart Phone

High Performance Testing Driven by Advanced Packaging



Large Package

CoWoS

High Power

High Frequency

Chiplet

CPO

High Speed

HyperSocket™

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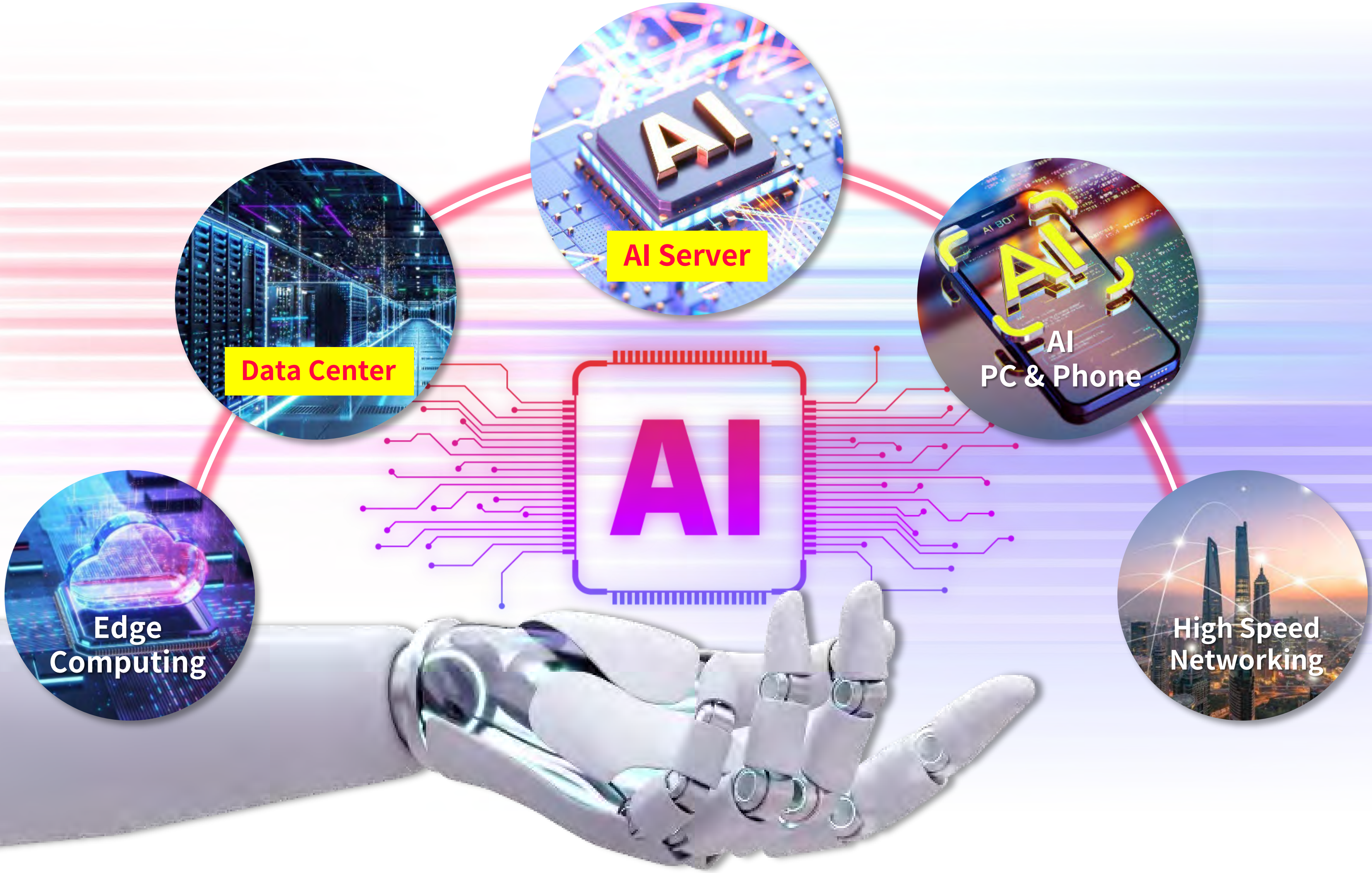
02 Industry Trend

Driving Force for AI



AI Server

Data Center

AI
PC & Phone

Edge
Computing

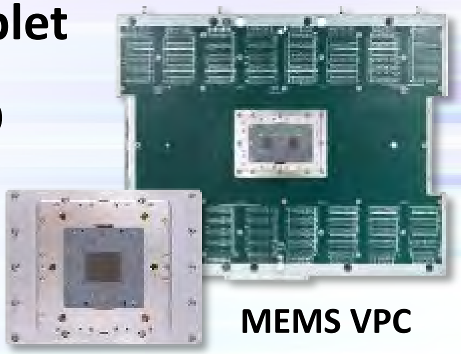
High Speed
Networking

Greater Importance on Chip Probing

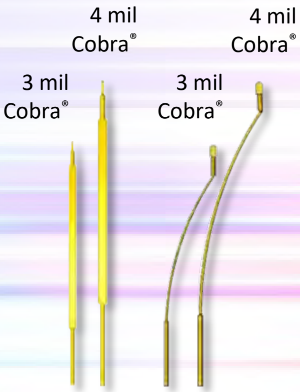
From the Shadows to the Spotlight

K.G.D Close to **K**nown **G**ood **D**ie

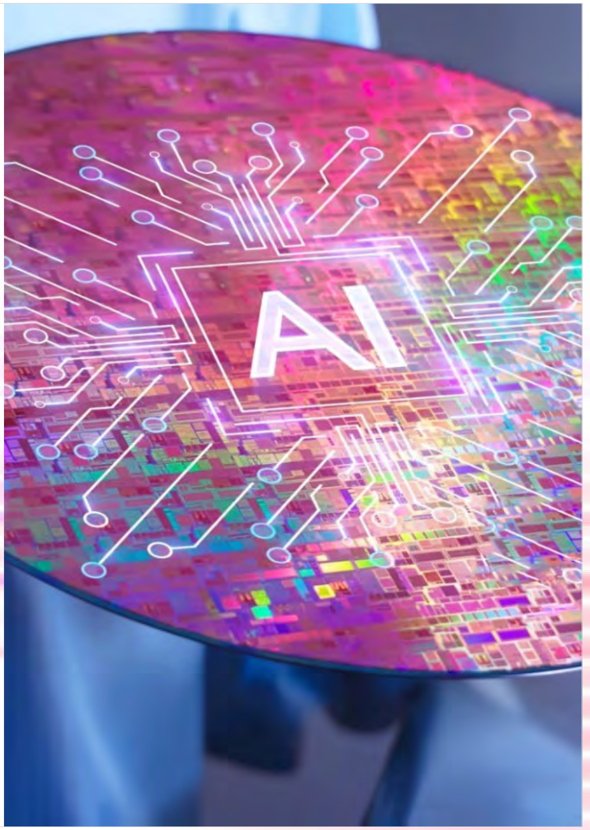
- **CoWoS**
- **Chiplet**
- **CPO**



MEMS VPC



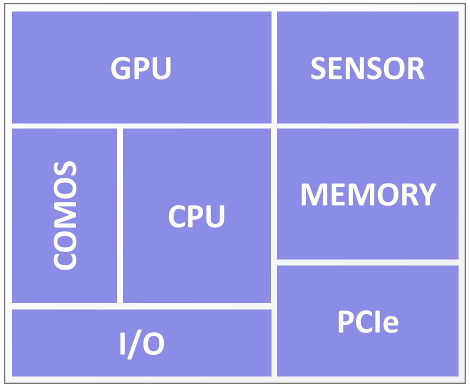
Cobra VPC



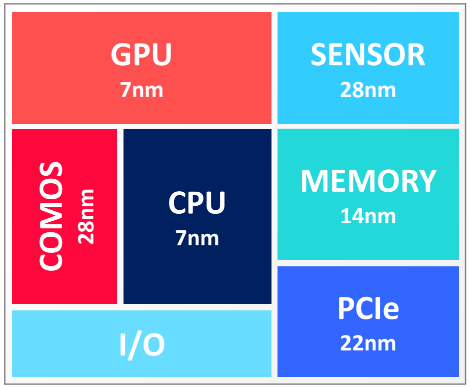
Known Good Die Is Required!

Probe Card Demand Induce

SoC One Probe Card



Chiplet Multiple Probe Card Demand

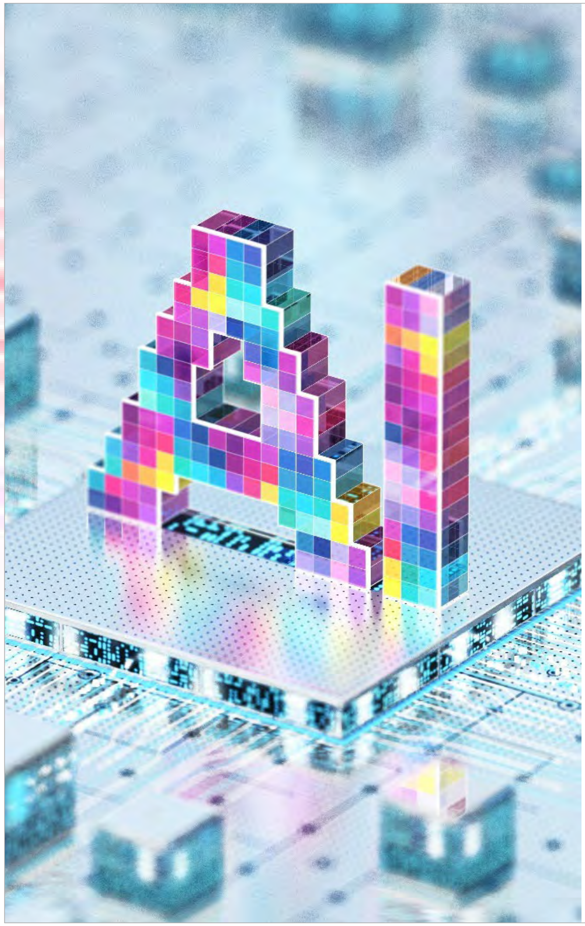


Source : Trend Force

Source: market.us

- Higher Pin Count
- Higher CCC
- Higher Speed
- Lower Force
- Smaller Pitch
- Wider Operation Temperature

Accelerated SLT Demand Driven by AI



2026-2030 CAGR

SLT & SFT

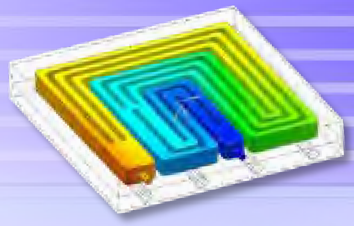
More than 15%

Greater than industry growth

Source: WinWay 2025

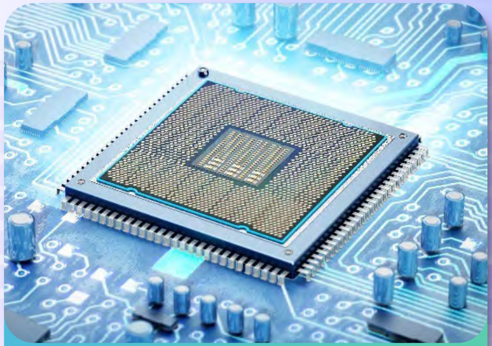
HyperSocket™

Coaxial Socket



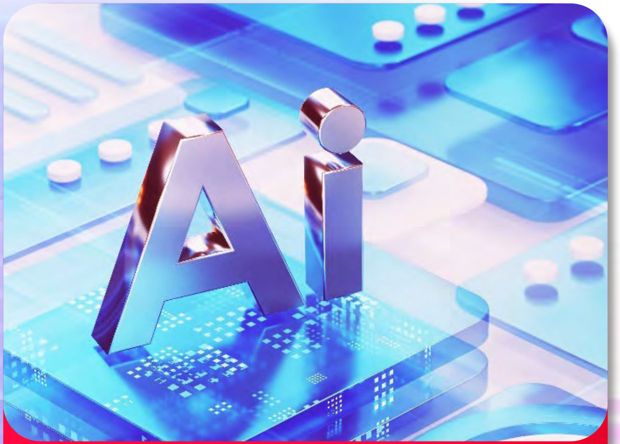
(Liquid Cooling)
Thermal System

Emerging Trend Toward Functional Burn-In



Reliability Burn-in

For all IC testing



Functional Burn-in

AI & HPC

Mass Production Burn-in

Automotive
CPU GPU

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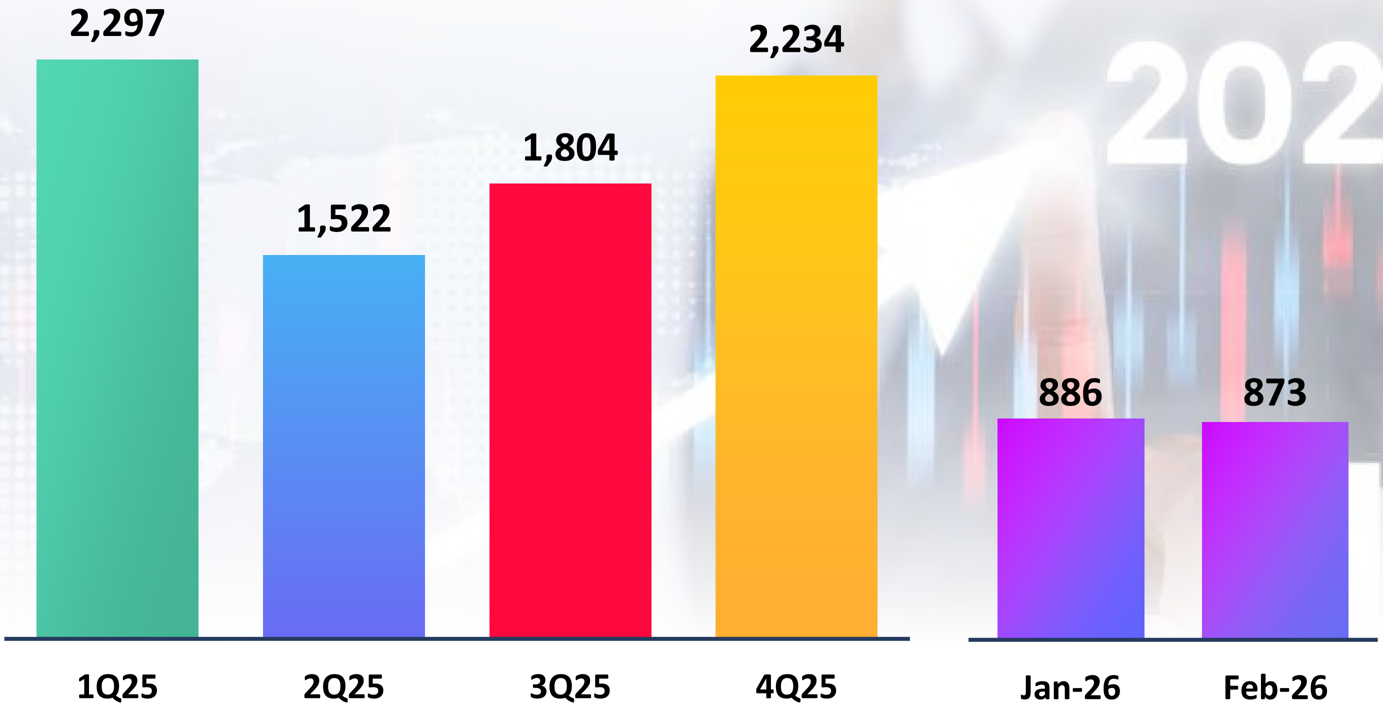
03 Financial Performance

Revenue Trend

QUARTERLY REVENUE

(NTD MILLION)



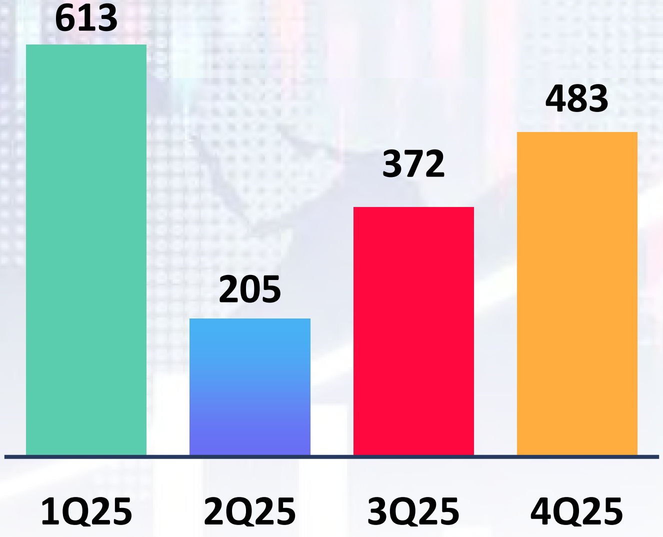
	1Q25	2Q25	3Q25	4Q25
YoY	114%	21%	-7%	45%
QoQ	49%	-34%	19%	24%

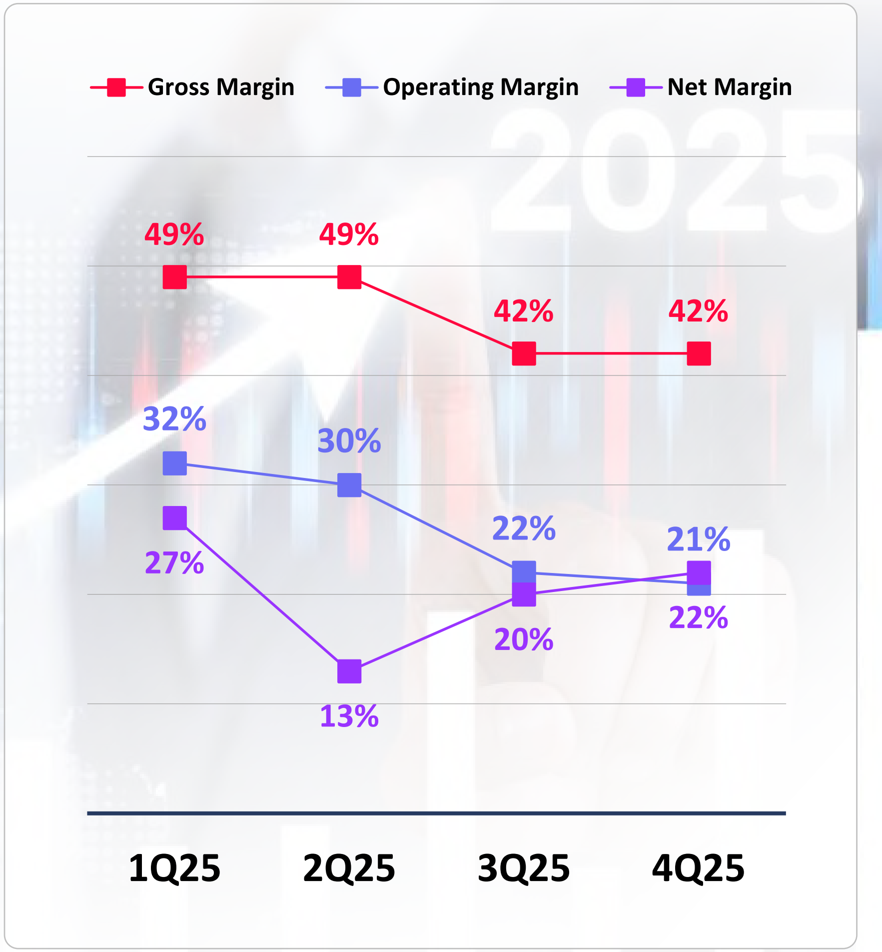
Profitability Trend

	2025 EPS	Dividend
(NT$)	46.93	50

EPS	17.21	5.76	10.43	13.53

NET INCOME (NTD M)

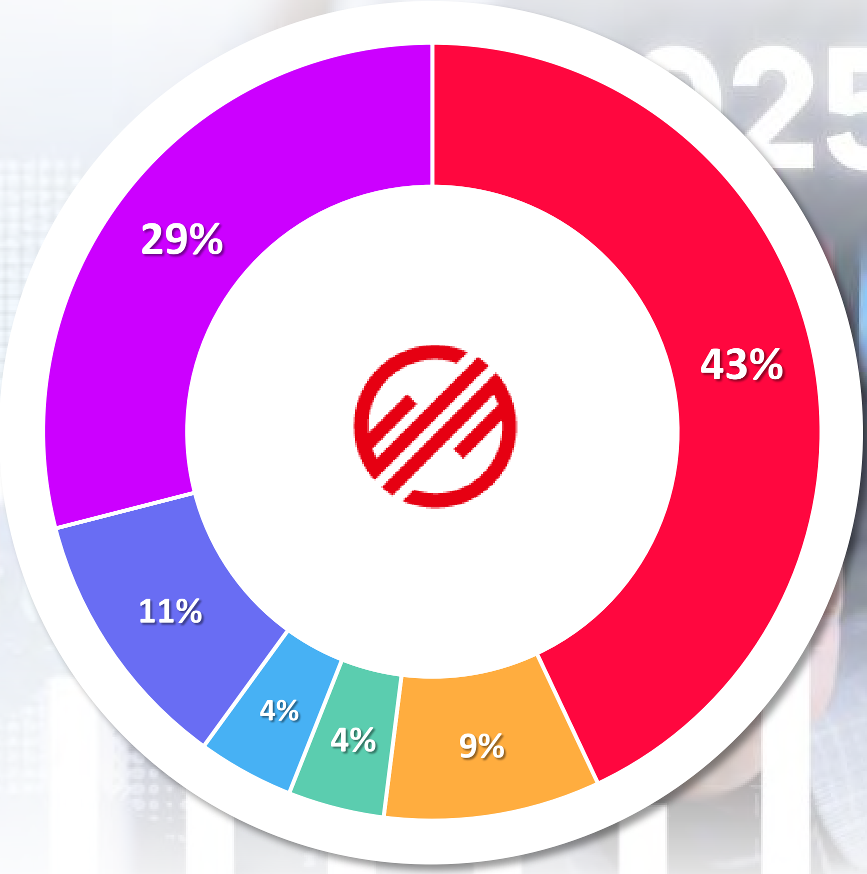




Revenue by Product Mix

Year 2025

🟥	**Coaxial Socket**	43 %
🟪	**Probe Card**	29 %
🟦	**Contact Element**	11 %
🟧	**RF & Plastic Socket**	9 %
🟩	**Burn-in Socket**	4 %
🟦	**Others**	4 %



Revenue by End Market

Year 2025

HPC & AI

48 %

Coaxial Socket

HyperSocket™

PC & Gaming

25 %

POP Plastic Socket

Smart Phone

5 %

POP Plastic Socket

Networking
Auto / Others

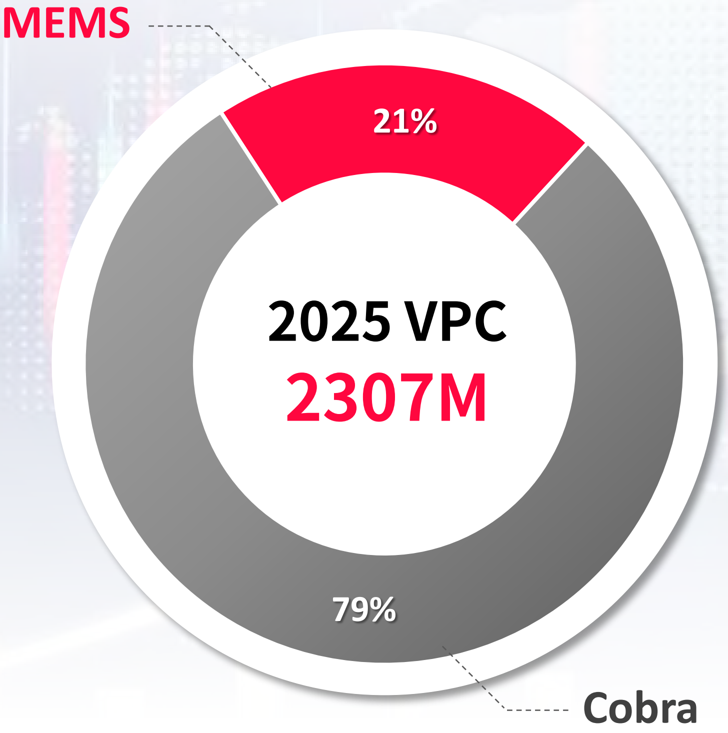
22 %

Plastic Socket

MEMS Probe Card

Year 2025

2025 MEMS VPC 21%



	Cobra	MEMS
2025 Q1	100%	0%
2025 Q2	99%	1%
2025 Q3	82%	18%
2025 Q4	10%	90%

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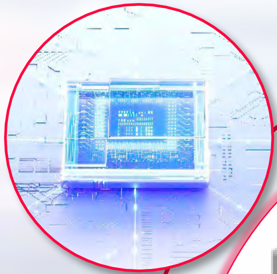
04

R&D Innovation

Innovative Semiconductor Test Interface Solution

HyperSocket^{TM}-Dual Film

Large Package



Larger contact area

Improved heat dissipation

Enhanced test stability

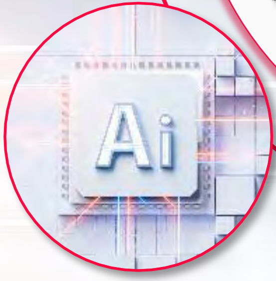
High Speed

Full metal shielding,

short-loop design

Test speed above 224Gbps

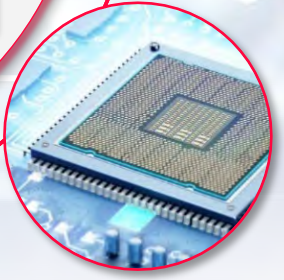
High Power



Various current pathways

Mitigating temperature rise

High Pin Counts



Zero Pre-load design

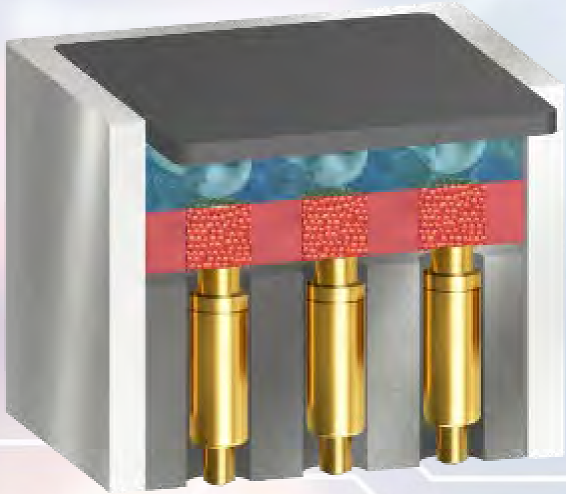
Reduced maintenance cost

Patent NO. TWI862047 TWI884802 TWI862191 TWI901161 CN20570508U

Patent Pending USA Malaysia

Innovative Semiconductor Test Interface Solution

Liquid Cooling Socket

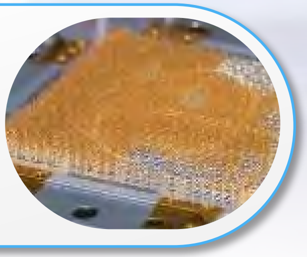


Patent NO. TWI901181

Extraordinary heat dissipation

Improved Test Stability For Advanced Packaging

Extend Spring Probe Lifespan



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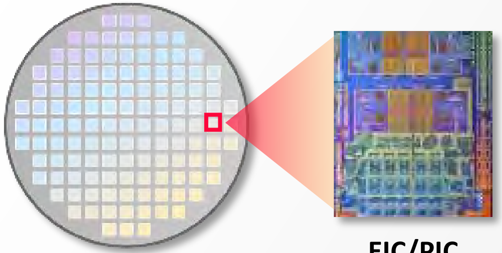
Co-Packaged Optics Test Solution

Wafer Level → Die Level



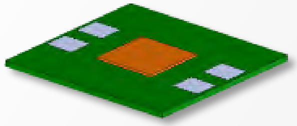
Silicon Photonic Wafer

EIC/PIC Die

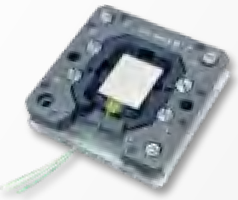
WLCSP Fine Pitch Socket
(PIC & EIC Wafer test)

Package Level

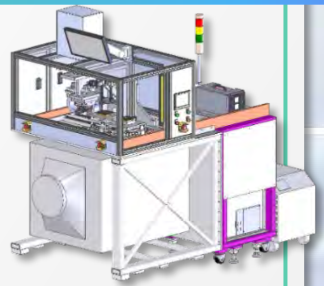
Optical Engine



CPO Substrate

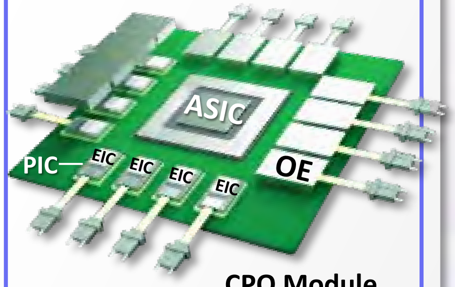


Optical and Electrical Test Socket
(Optical Engine)



Double Sided Probing System

Module Level



CPO Module
Source: ASE Holdings

Coaxial Socket

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High Power Thermal Solution

E-Flux6.0 3500W Liquid Cooling System

2026

2030

203x

~2,000W

~4,000W

~6,000W

🟦 GPU

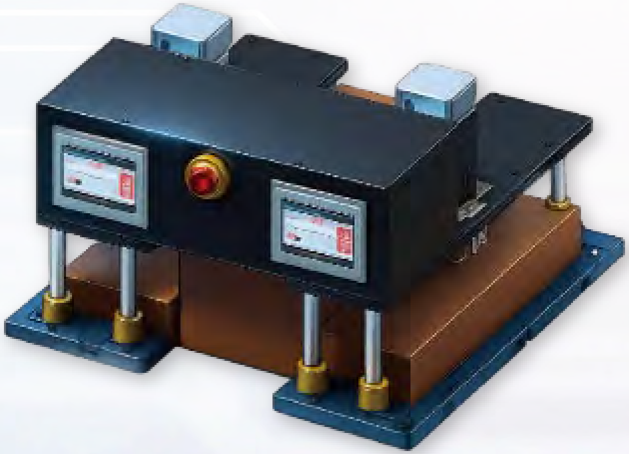
🟩 HBM

⬜ Interposer

AI Server Board-Level Test

AI Data Center

AI Server



SLT Plunger System

Spring Probe Manufacturing

Socket All in House

Cost Optimization

Balanced insourcing, better cost structure

Self-Sufficiency

Autonomy of critical process technology

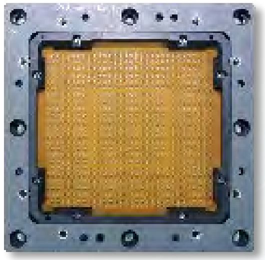
Quality Assurance

Greater customer experience

Operational Resilience

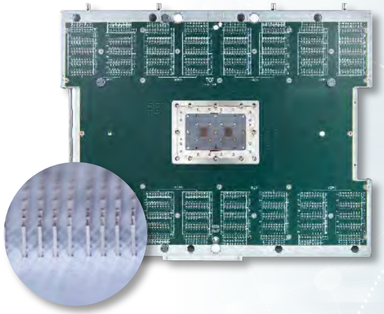
More flexible, agile lead time

Pillars of Business Growth



HyperSocket™

Positioned for advanced packaging



MEMS Probe Card

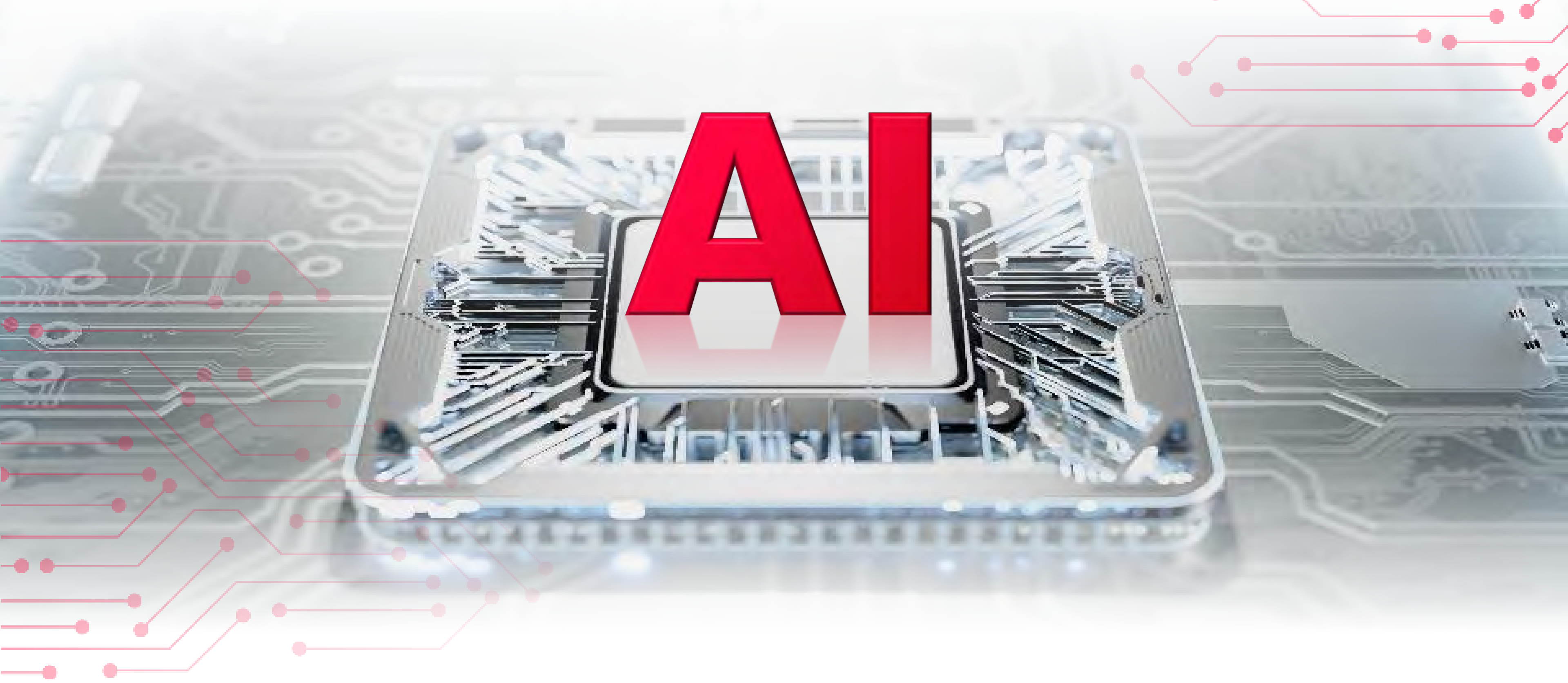
Localized service for AI/HPC

Functional Burn-in

Pioneer in emerging application

Challenges and Opportunities:

Breakthrough in Advanced Packaging and Mastering Future of Testing



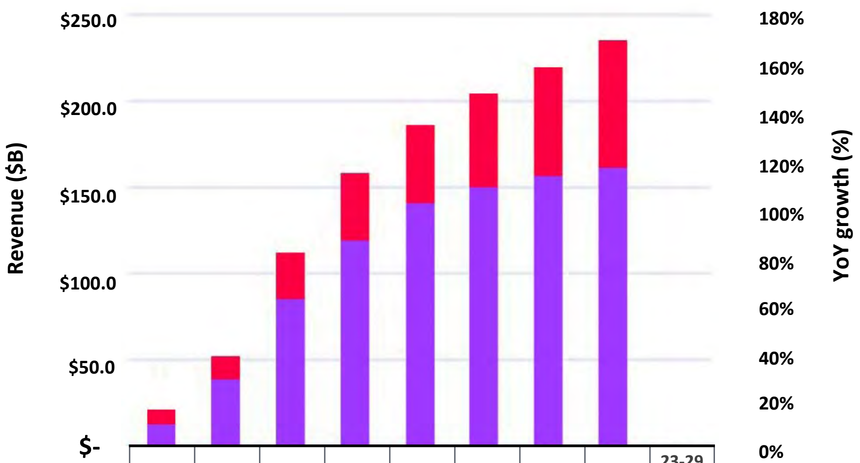
Advanced Package Application and Market Trend

Data Center AI Chip & ASIC

GPU ASIC

Datacenter GPU and AI ASIC revenue forecast

AI ASIC CAGR **35.0%**   GPU CAGR **26.9%**

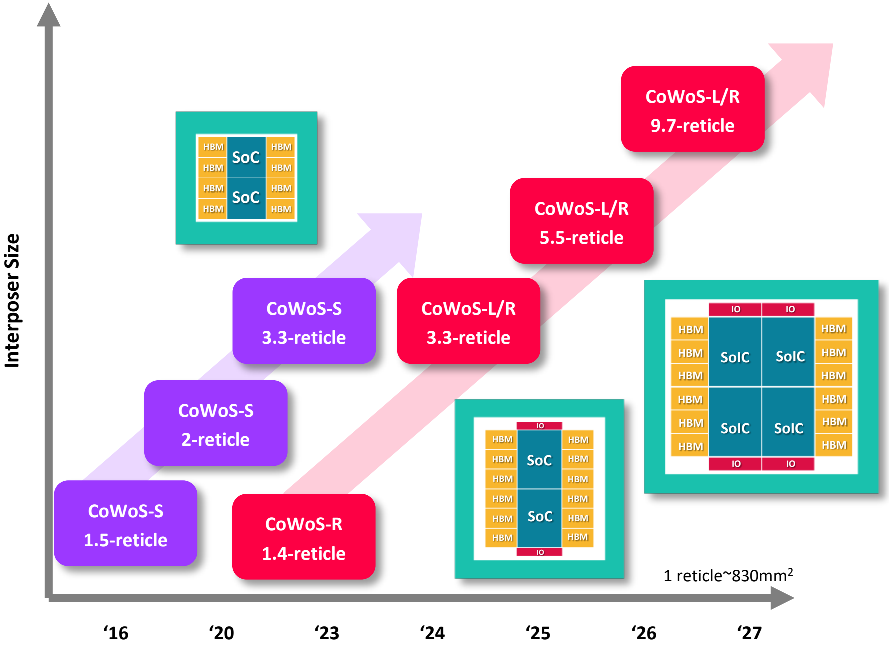


	2022	2023	2024	2025	2026	2027	2028	2029	23-29 CAGR
🟥 AI ASIC	$6.3	$11.8	$25.3	$36.8	$45.1	$52.5	$61.1	$71.1	35.0%
🟪 GPU	$12.6	$38.8	$85.6	$119	$139	$150	$157	$162	26.9%
Total	$18.9	$50.5	$110	$156	$185	$202	$218	$233	29.0%
YoY(%)	38%	167%	120%	41%	19%	10%	8%	7%	

Source: Yole

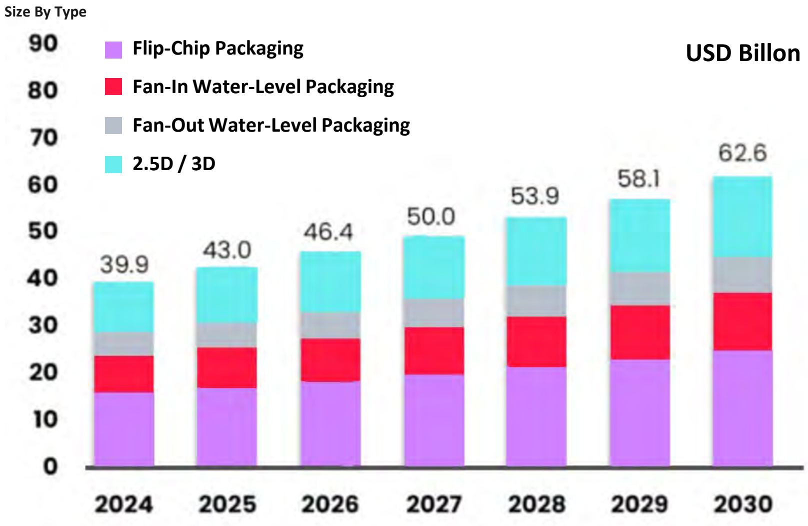
Advanced Package Application and Market Trend

CoWoS Enables AI Compute Scaling



Source: TSMC

Global Advanced Semiconductor Packaging Market

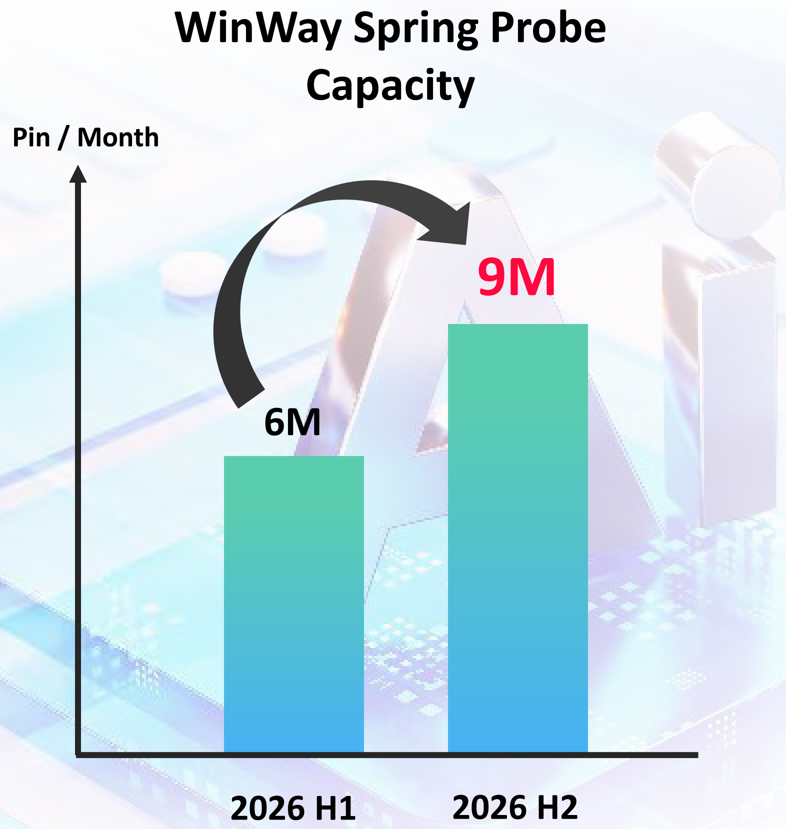


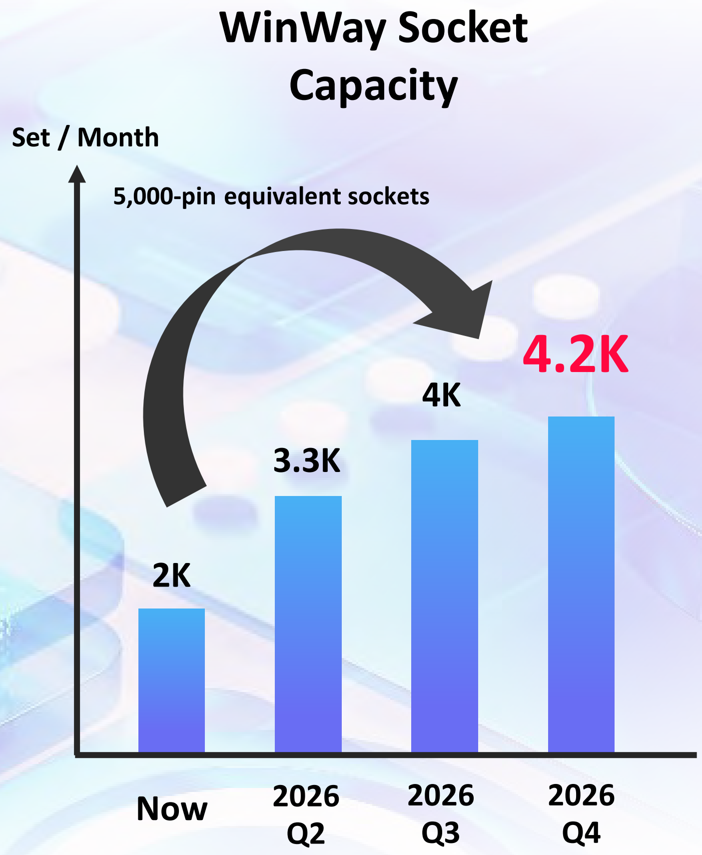
The Forecasted Market Size for 2030 is USD **$62.6B**

The Market will Grow At the CAGR of **7.8%**

Source: market.us

Accelerating Capacity Expansion





Renwu Facility I:

Completion

March 2026

Production

Begins from
April and May 2026

Renwu Facility II:

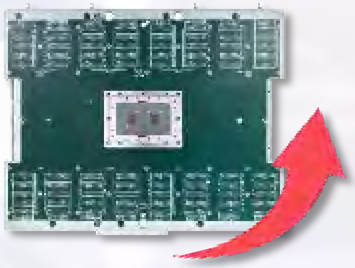
Construction Begin	Construction Complete	Production
Jul. 2026	Jan. 2028	Feb. 2028

Total Area: Approx. 6300 *ping* (~20,826 m^2)

Significant Increase in Testing Time

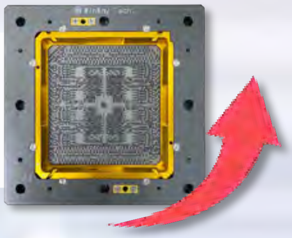
Longer Wafer Sort Test Time

MEMS and Cobra Probe card



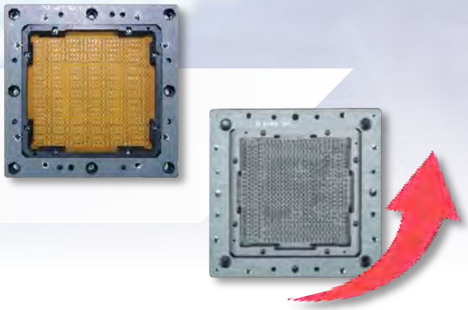
Longer FT (ATE) Test Time

Plastic, Coaxial and HyperSocket™



Longer SLT Test Time

Coaxial and HyperSocket™



More Test Insertions

More Reliability Test Insertion

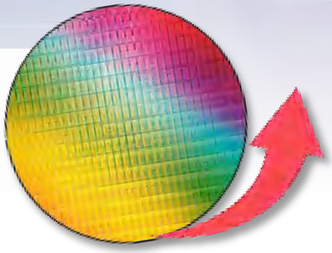
Functional Burn-In Socket

Bigger and Bigger Device Package
Higher and Higher Device Power Consumption

HyperSocket™ and HyperSocket™ -DF

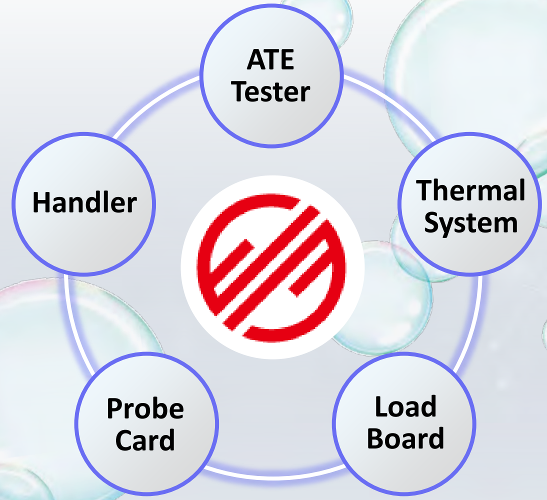
Longer and Longer Fab In-process Time

Fab and OSAT expansion drive equipment demand



Industry Alliance and Integration Across Heterogeneous Disciplines

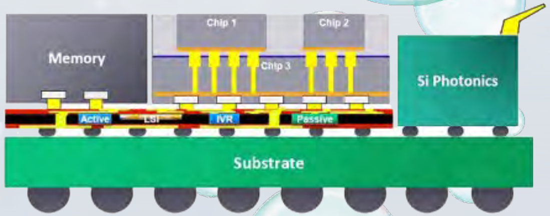
Alliance **Integration** **Heterogeneous**



AI

Artificial Intelligence

CPU、GPU、HPC



Source: TSMC

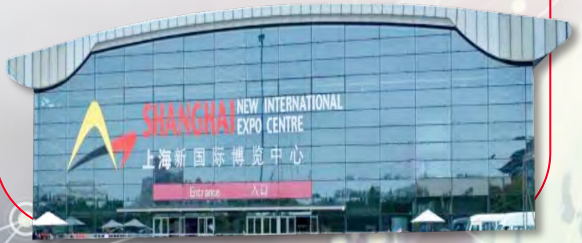
HI

SEMICON China

2026.03.25—27

China

Shanghai New International Expo Centre



SEMICON SEA

2026.05.05—07

Malaysia

Malaysia International Trade & Exhibition Centre

Investor Conference

2026.05.26

Taiwan

Grand Hyatt Taipei

Q & A

Your Trusted Partner in Semiconductor Testing

TWSE 6515

THANK YOU

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